**COVER LETTER**

Date:

For,

TECHNOLOGY DEVELOPMENT BOARD (TDB)

**Scheme**: \*\*\*insert application scheme name (e.g. –**THE INDIA – SPAIN PROGRAMME OF COOPERATION ON INDUSTRIAL RESEARCH AND DEVELOPMENT**)\*\*\*

**Application Number**: \*\*\*insert application number\*\*\*

**PROJECT TITLE**: \*\*\*insert project title\*\*\*

**Subject: Proposal application for \*\*\*insert scheme name\*\*\* by \*\*\*insert your company name\*\*\***

Dear sir/ma’am,

We would like to take this opportunity to introduce and apply for our project - **\*\*\*insert project**

**name\*\*\*** under the **\*\*\*insert scheme name\*\*\*** call which falls under the **\*\*\*insert focus sector**

**name**\*\*\* focus sector.

Brief about our project –

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Our **\*\*\*insert country name (e.g. Spain)\*\*\*** partner for this project is **\*\*\*insert partner**

**name\*\*\*** and they possess expertise in this domain since \*\*\*insert number of years\*\*\*.

\*\*\*insert any other relevant information (if any)\*\*\*

I hereby state that all information provided for this application is self-attested and is provided in

honesty to the best of my knowledge.

Regards,

*\*\*\*insert your signature\*\*\**

*\*\*\*insert your company stamp\*\*\**

*\*\*\*insert your name\*\*\**

*\*\*\*insert your designation\*\*\**

Signing Authority

*\*\*\*NOTE - cover letter to be on the IPC’s official letter head AND should not exceed 1 page. Remove*

*NOTE before final submission\*\*\**